

# **NCE N-Channel Super Trench II Power MOSFET**

## **Description**

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

#### **Application**

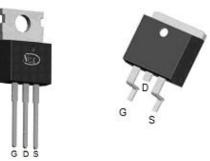
- DC/DC Converter
- •Ideal for high-frequency switching and synchronous rectification

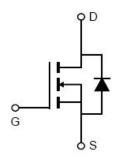
#### **General Features**

- $V_{DS}$  =85V, $I_D$  =260A  $R_{DS(ON)}$ =2.0m $\Omega$  , typical (TO-220)@  $V_{GS}$ =10V  $R_{DS(ON)}$ =1.8m $\Omega$  , typical (TO-263)@  $V_{GS}$ =10V
- Excellent gate charge x R<sub>DS(on)</sub> product(FOM)
- Very low on-resistance R<sub>DS(on)</sub>
- 175 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!







**Schematic Diagram** 

## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP023N85M	NCEP023N85M	TO-220	-	-	-
NCEP023N85MD	NCEP023N85MD	TO-263	-	-	-

#### Absolute Maximum Ratings (T<sub>c</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	85	V
Gate-Source Voltage	V <sub>G</sub> s	±20	V
Drain Current-Continuous	I <sub>D</sub>	260	А
Drain Current-Continuous(T <sub>C</sub> =100°C)	I <sub>D</sub> (100℃)	195	Α
Pulsed Drain Current	I <sub>DM</sub>	1000	Α
Maximum Power Dissipation	P <sub>D</sub>	300	W
Derating factor		2	W/℃
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	2880	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$



# NCEP023N85M, NCEP023N85MD

#### **Thermal Characteristic**

		Thermal Resistance, Junction-to-Case	Rejc	0.5	°C/W
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# Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

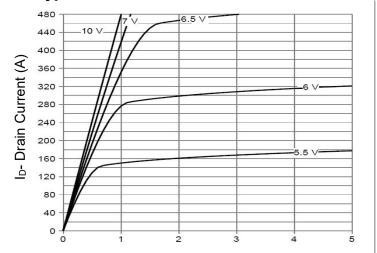
Parameter	Symbol	Condition	on	Min	Тур	Max	Unit
Off Characteristics	•			•			•
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =2	50µA	85		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =85V,V <sub>GS</sub>	s=0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20 $V$ , $V_{D}$	os=0V	-	-	±100	nA
On Characteristics (Note 3)	•			•	•		
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =2	250μA	2.0	3.0	4.0	V
Danier Courses Our Otata Basistana	Б	TO-220		-	2.0	2.3	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =130A	TO-263		1.8	2.3	mΩ
Gate resistance	R <sub>G</sub>			1	-	4	Ω
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =130A			200	-	S
Dynamic Characteristics (Note4)	•			'			'
Input Capacitance	C <sub>lss</sub>	14 401414	0) (	-	14500	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =40V,V <sub>GS</sub>	•	-	2100	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MH	IZ	-	105	-	PF
Switching Characteristics (Note 4)				•			•
Turn-on Delay Time	t <sub>d(on)</sub>			-	41	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}=40V,I_{D}=$	130A	-	37	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =10V,R <sub>G</sub> =	=1.6Ω	-	103	-	nS
Turn-Off Fall Time	t <sub>f</sub>			-	38	-	nS
Total Gate Charge	Qg	- V <sub>DS</sub> =40V,I <sub>D</sub> =130A, - V <sub>GS</sub> =10V		-	240	-	nC
Gate-Source Charge	$Q_{gs}$			-	61		nC
Gate-Drain Charge	$Q_{gd}$			-	72		nC
Drain-Source Diode Characteristics	•			•			
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =1	30A	-		1.2	V
Diode Forward Current	Is			-	-	260	Α
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> =	= 130A	-	106	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µ	IS <sup>(Note3)</sup>	-	309	-	nC

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25  $^{\circ}\text{C}$  ,V\_DD=40V,V\_G=10V,L=0.5mH,Rg=25 $\Omega$

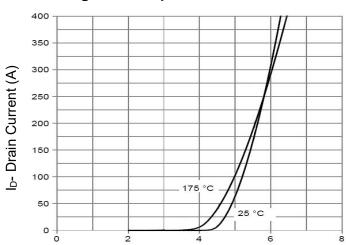


## **Typical Electrical and Thermal Characteristics**



Vds Drain-Source Voltage (V)

# **Figure 1 Output Characteristics**



Vgs Gate-Source Voltage (V)

## **Figure 2 Transfer Characteristics**

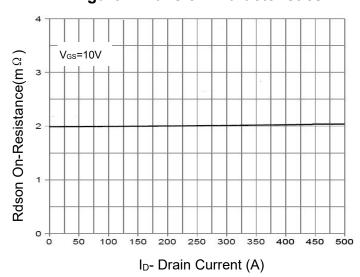
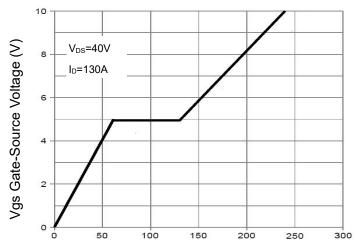


Figure 3 Rdson- Drain Current

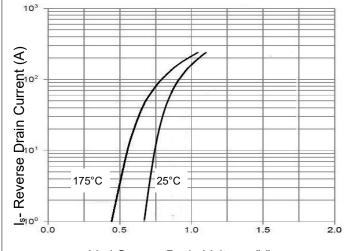
T<sub>J</sub>-Junction Temperature(°C)

### Figure 4 Rdson-Junction Temperature



Qg Gate Charge (nC)

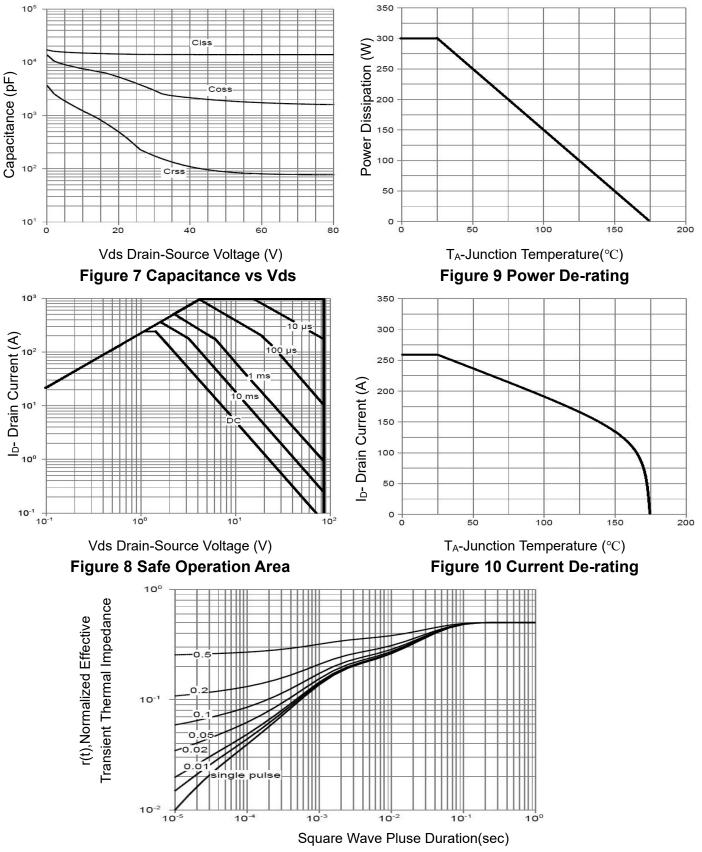
#### Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward

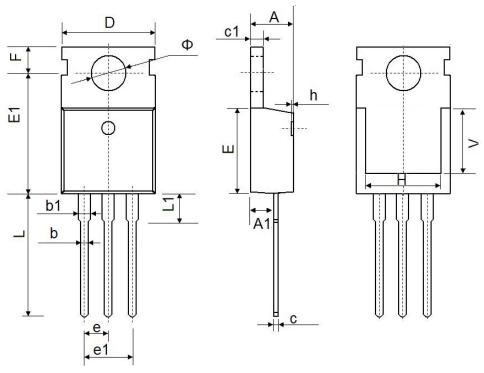




**Figure 11 Normalized Maximum Transient Thermal Impedance** 



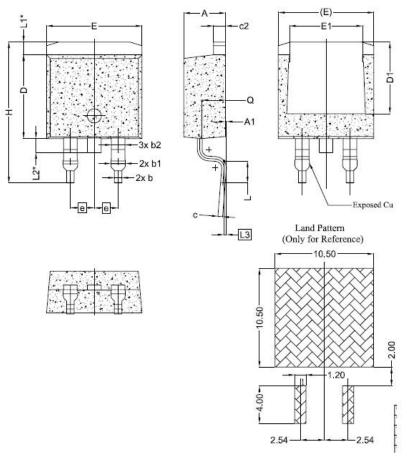
# **TO-220-3L Package Information**



0	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
E	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.540	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	6.900	REF.	0.276 REF.		
Ф	3.400	3.800	0.134	0.150	



# **TO-263-2L Package Information**



SYMBOL	DIMENSIONS			
SYMBOL	MIN.	NOM.	MAX.	
А	4.24	4.44	4.64	
A1	0.00	0.10	0.25	
b	0.70	0.80	0.90	
b1	1.20	1,55	1.75	
b2	1,20	1,45	1,70	
С	0.40	0.50	0.60	
c2	1,15	1,27	1,40	
D	8.82	8.92	9.02	
D1	6.86	7.65		
E	9.96	10,16	10,36	
E1	6.89	7.77	7,89	
е		2,54 BSC		
Н	14,61	15,00	15,88	
L	1.78	2.32	2.79	
L1	1.36 REF.			
L2	1.50 REF.			
L3	0.25 BSC			
Q	2,30	2.48	2.70	

http://www.ncepower.com

# NCEP023N85M, NCEP023N85MD



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